

# MELAMINE MOULDING COMPOUND WITH ANTI-MICROBIAL AND ANTI-FUNGAL PROPERTIES

## Technical leaflet

Emsig Manufacturing has acquired a Melamine Molding Compound, developed by a resin supplier, which after being molded shows very effective anti-microbial and anti-fungal activity.

These properties are achieved by completely mixing Carsept-80 micro-biocide with the molding compound in the course of its production process. The Carsept-80 slowly diffuses to the surface of the molding object, thus inhibiting the survival of microorganisms. Since Carsept-80 is part of the formulation and present in the bulk of the plastic, its activity continues indefinitely. This means that the foreseeable micro-biocidal activity will be maintained for the lifetime of the product. The mechanical, physical and processing properties of the Melamine Molding Compound are not affected by the presence of the Carsept-80 micro-biocide. The micro-biocidal properties of the Carsept-80 treated Discs molded from Melamine Molding compound, were tested on Agar for different microorganisms. The results of these tests are given in the following table

### Microbiological inhibition of different microorganisms by molded melamine discs containing Carsept-80

	<u>Blank</u>	<u>With Carsept-80</u>
Staphylococcus Aureus	~103	0
Streptococcus Faecalis	~103	0
Salmonella Typhimurium	~103	0
Saccharomyces Cerevisiae	~103	0
Pseudomonas Aeruginosa	~103	0
Candida Albicans	~103	0
Aspergillus Niger	~103	0

This test was performed as a "Spot Test" with 2 discs on the same plate and one was a Molded Melamine Disc with Carsept-80 and the other was a control of a Blank Molded Melamine Disc (without Carsept-80).

Incubation at 37° for the bacteria and 30° for Candida and Aspergillus.

**Note:** The Information and statements herein are believed to be reliable, but are not to be construed as a warranty or representation for which we assume legal responsibility Users should undertake sufficient verification and testing to determine the suitability for their particular purpose of any information on products referred to herein.

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